Page 2: BLOCK DIAGRAM

Page 3: SELF POWER + REGULATOR + FUSE + LDO

Page 4: ANALOG FRONT END OPAMP + TEMP SENSOR

Page 5: MCU + LED INDICATION

Page 6: HARDWARE - MISCELLANEOUS
Signal Processing Subsystem for ACB/MCCB

Auxiliary DC or Rectified CT input

Breaker Enclosure

Current Transformer

MOSFET Shunt Regulation

Rectified current, MOSFET CSD105 37NKCS

LM2993

self power PWM control

LM5017 DC-DC converter

3.3V LDO TPS7A553

buffer

LM4041

3.3V

JTAG 14 pin

I2C SPI

SPI I2C GPIO UART Screw type connector

MSP430FR5069RGZ

self power PWM control

Crystal: 32K 8M

LM3864

LMT67

Gain: X 2

Gain: X 5.7

Gain: X 2

Gain: X 5.7

Gain: X 2

Gain: X 5.7

Gain: X 5.7

Gain: X 5.7

Gain: X 2
Enter name of project lead
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PCB Number: TIDA-00498
PCB Rev: E2

Label Table

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Assembly Note

Z23
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Z24
These assemblies are ESD sensitive, ESD precautions shall be observed.

Z25
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Contact:
http://www.ti.com/support

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